

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

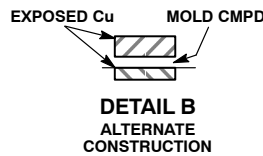
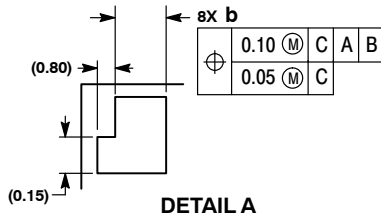
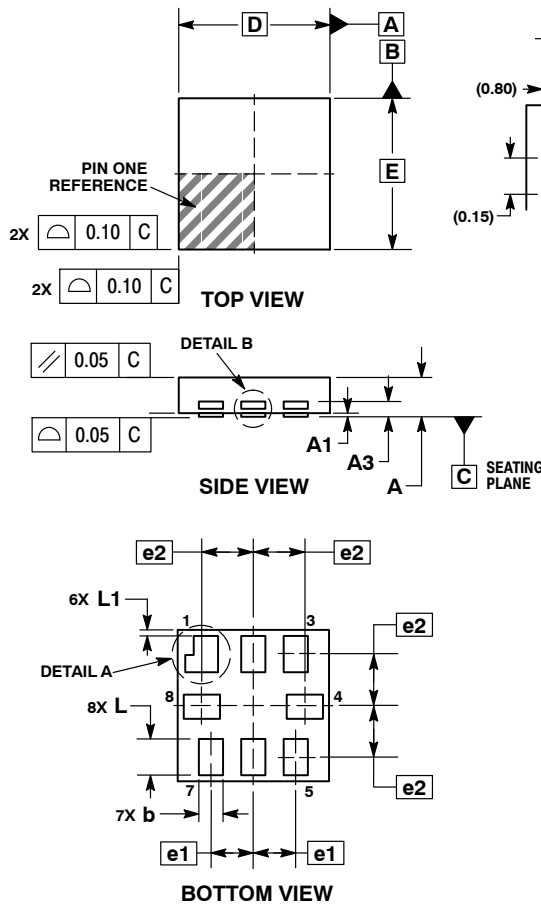
ON Semiconductor®



SCALE 4:1

**XQFN8 1.25x1.25, 0.4P**  
CASE 723AA  
ISSUE O

DATE 20 SEP 2011



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25 mm FROM THE TERMINAL TIP.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.40
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.25 BSC	
E	1.25 BSC	
e1	0.40 BSC	
e2	0.45 BSC	
L	0.25	0.35
L1	0.05	---

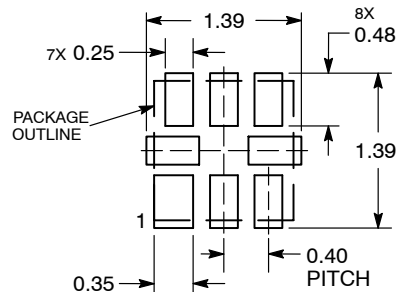
### GENERIC MARKING DIAGRAM\*



X = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

### RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	XQFN8, 1.25 X 1.25, 0.4 P	<b>PAGE 1 OF 2</b>

